Journal of Electronic Packaging

Guest Editorial

Special Section on InterPACK2021

The International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems (InterPACK) is a flagship conference of ASME Electronic and Photonic Packaging Division (EPPD). It has served as an international forum within the ASME society to share and exchange latest progresses in the research, development, and applications of electronic and photonic packaging since 1992. The aim of *ASME Journal of Electronic Packaging* (JEP) Special Section for InterPACK is to publish outstanding papers from technical tracks of InterPACK2021, which was held virtually amid COVID-19 pandemic worldwide. This Special Section of the ASME JEP publishes nine papers presented at the InterPACK2021 in the areas of electronics and photonics packaging, micro-electronics reliability, and advanced thermal management from the silicon, package, to data center level. All nine papers published in this JEP Special Section for InterPACK2021 went through a standard peer-review process for journal papers published by ASME.

The micro-electronics industry is facing challenges to meet demanding performance and functional needs of high-performance computing (HPC), artificial intelligence (AI), 5 G/mm Wave, and power electronic devices. In order to close this gap, in parallel with new breakthroughs in advancing silicon node, the semiconductor industry is also embracing advanced integrated circuits (IC) packaging technologies, including heterogeneous integration, 2.5D/3D IC packaging, chiplet, additive manufacturing, novel modeling and characterization techniques, and others. This Special Section reflects latest progresses in the IC packaging by publishing nine papers presented at ASME InterPACK2021. We gratefully acknowledge all the authors who have revised their original conference papers for this Special Section and the reviewers who have spent tremendous time and efforts to help improve overall quality of the papers for this Special Section. We also would like to thank the ASME JEP Editor-in-Chief (EIC), Professor Shi-Wei Ricky Lee for his guidance and support, and the assistant to EIC, Dr. Jeffery Lo for his help in this journey.

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